



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-06-16
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	1YNB*0158BG6	A	Z6HA	2014-06-16
Amount	UoM	Unit type	ST ECOPACK Grade	
11.60	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2x2x0.6	8	No lead	
Comment	UFSON 2x2x0.6 8 PITCH 0.5; MD valid for CP:LM2904Q2T.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	1YNB*0158BG6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.403	mg	supplier	Die	Silicon (Si)	7440-21-3		0.39	mg	967742	33621
Silicon die					metallization	Aluminium (Al)	7429-90-5		0.006	mg	14888	517
Silicon die					passivation	Silicon Nitride (SiN)	68034-42-4		0.003	mg	7444	259
Silicon die					passivation	Silicon Oxide(SiO2)	7631-86-9		0.004	mg	9926	345
Lead frame	Leadframe	3.766	mg	Supplier	Alloy	Copper (Remaining)	7440-50-8		3.549	mg	942379	305948
Lead frame						Silicon (0.25-1.2%)	7440-21-3		0.018	mg	4780	1552
Lead frame					Alloy	Nickel (2.2-4.2%)	7440-02		0.131	mg	34785	11293
Lead frame					Alloy	Magnesium (0.05-0.3%)	7439-95-4		0.006	mg	1593	517
Lead frame					Alloy	Iron (0.2% max)	7439-89-6		0.004	mg	1062	345
Lead frame					Alloy	Zinc (1.0% max)	7440-66-6		0.018	mg	4780	1552
Lead frame					Alloy	Manganese (0.10% max)	7439-96-5		0.002	mg	531	172
Lead frame					Alloy	Silver (0.5~1.5%)	7440-22-4		0.038	mg	10090	3276
Die Attach	Die Attach	0.139	mg	supplier	Epoxy	Aluminium oxide (20-35%)	1344-28-1		0.042	mg	302158	3621
Die Attach						Epoxy	Diethylene glycol monoethyl ether acetate (2	112-15-2	0.055	mg	395683	4741
Die Attach						Epoxy	Epoxy resin (1-10%)	25068-38-6	0.01	mg	71942	862
Die Attach						Epoxy	Epoxy resin (10-30%)	Proprietary	0.028	mg	201439	2414
Die Attach						Epoxy	Aromatic amine (1-5%)	Proprietary	0.004	mg	28777	345
Bonding wire	Bonding wire	0.083	mg	supplier	Bonding wire	Au	7440-57-5		0.083	mg	1000000	7155
Encapsulation	Encapsulation	7.015	mg	supplier	Molding compound	Silica Fused (85~95%)	60676-86-0		6.574	mg	937135	566724
Encapsulation					Molding compound	Epoxy Resin (1~5%)	Proprietary		0.21	mg	29936	18103
Encapsulation					Molding compound	Phenol Resin (1~5%)	Proprietary		0.21	mg	29936	18103
Encapsulation					Molding compound	Carbon Black (0.1~0.5%)	1333-86-4		0.021	mg	2994	1810
Finishing	Finishing	0.194	mg	supplier	Connection coating	Sn	7440-31-5		0.194	mg	1000000	16724